

L Number	Hits	Search Text	DB	Time stamp
4	4961	solder\$1 with (differ\$5 or higher or lower or earlier or later) with (melting or molton or melt\$2 or solidif\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 12:32
5	749	(solder\$1 with (differ\$5 or higher or lower or earlier or later) with (melting or molton or melt\$2 or solidif\$5)) and (solder near2 second)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 12:22
6	309	(solder\$1 with (differ\$5 or higher or lower or earlier or later) with (melting or molton or melt\$2 or solidif\$5)) and (chip with solder\$1 with electrode\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 12:42
7	2166	solder\$1 near4 ((differ\$5 or higher or lower or earlier or later) adj2 (melting or molton or melt\$2 or solidif\$5) adj2 (temperature\$1 or point\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 12:35
8	166	(solder\$1 near4 ((differ\$5 or higher or lower or earlier or later) adj2 (melting or molton or melt\$2 or solidif\$5) adj2 (temperature\$1 or point\$1))) and (chip with solder\$1 with electrode\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 12:49
9	810	(solder\$1 near4 ((differ\$5 or higher or lower or earlier or later) adj2 (melting or molton or melt\$2 or solidif\$5) adj2 (temperature\$1 or point\$1))) and (chip with solder\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 12:49
10	644	((solder\$1 near4 ((differ\$5 or higher or lower or earlier or later) adj2 (melting or molton or melt\$2 or solidif\$5) adj2 (temperature\$1 or point\$1))) and (chip with solder\$1)) not ((solder\$1 near4 ((differ\$5 or higher or lower or earlier or later) adj2 (melting or molton or melt\$2 or solidif\$5) adj2 (temperature\$1 or point\$1))) and (chip with solder\$1 with electrode\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 13:05
11	3	"5888580"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 13:05
12	16	"5888850"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/21 13:05